		QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS SGDS015 - FEBRUARY 2002
	Q Devices Meet Automotive Performance Requirements	D OR PW PACKAGE (TOP VIEW)
	Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval	10E 1 14 V _{CC} 1A 2 13 40E 1Y 3 12 4A
	EPIC™ (Enhanced-Performance Implanted CMOS) Process	20E [4 11] 4Y 2A [5 10] 30E
•	Operating Range 2-V to 5.5-V V _{CC}	2Y [6 9] 3A
	Latch-Up Performance Exceeds 250 mA Per JESD 17	GND [7 8] 3Y

description

The SN74AHC125Q is a quadruple bus buffer gate featuring independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (\overline{OE}) input is high. When \overline{OE} is low, the respective gate passes the data from the A input to its Y output.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T _A	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
4000 to 10500	SOIC – D	Tape and reel	SN74AHC125QDR	AHC125Q		
–40°C to 125°C	TSSOP – PW	Tape and reel	SN74AHC125QPWR	HA125Q		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	each bu	uffer)
INPU	JTS	OUTPUT
ŌE	Α	Y
L	Н	Н
L	L	L
Н	Х	Z



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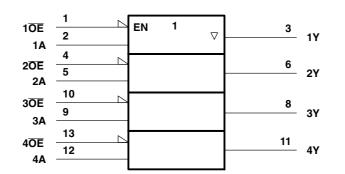


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SN74AHC125Q

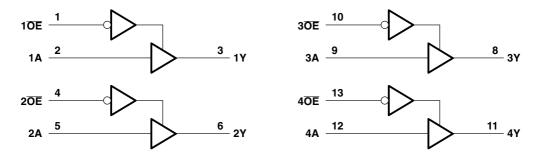
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Output voltage range, V_O (see Note 1) Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) Continuous output current, I_O ($V_O = 0$ to V_{CC}) . Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 2):	D package	$\begin{array}{c} -0.5 \ V \ to \ 7 \ V \\ -0.5 \ V \ to \ V_{CC} + 0.5 \ V \\ -20 \ mA \\ \pm 20 \ mA \\ \pm 25 \ mA \\ \pm 50 \ mA \\ 86^\circ C/W \end{array}$
Storage temperature range, T _{stg}	PW package	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2	5.5	V
		$V_{CC} = 2 V$	1.5		
VIH	High-level input voltage	V _{CC} = 3 V	2.1		V
		V _{CC} = 5.5 V	3.85		
		$V_{CC} = 2 V$		0.5	
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9	V
		V _{CC} = 5.5 V		1.65	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V_{CC}	V
		$V_{CC} = 2 V$		-50	μA
I _{OH}	High-level output current	$V_{CC}=3.3~V\pm0.3~V$		-4	mA
		V_{CC} = 5 V ± 0.5 V		-8	
		$V_{CC} = 2 V$		50	μA
l _{OL}	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4	
		V_{CC} = 5 V ± 0.5 V		8	mA
		$V_{CC}=3.3~V\pm0.3~V$		100	
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		20	ns/V
T _A	Operating free-air temperature		-40	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			Т	₄ = 25°C	;				
PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	MIN	MAX	UNIT	
		2 V	1.9	2		1.9			
	l _{OH} = -50 μA	3 V	2.9	3		2.9			
V _{OH}		4.5 V	4.4	4.5		4.4		v	
0.11	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48			
	I _{OH} = -8 mA	4.5 V	3.94			3.8			
		2 V			0.1		0.1		
	l _{OL} = 50 μA	3 V			0.1		0.1		
V _{OL}		4.5 V			0.1		0.1	v	
	I _{OL} = 4 mA	3 V			0.36		0.5		
	I _{OL} = 8 mA	4.5 V			0.36		0.5		
lı	$V_1 = 5.5 V \text{ or GND}$	0 V to 5.5 V			±0.1		±1	μA	
I _{OZ}	$V_{O} = V_{CC}$ or GND	5.5 V			±0.25		±2.5	μA	
I _{CC}	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4		40	μA	
Ci	$V_I = V_{CC}$ or GND	5 V		4	10			pF	



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	TA	= 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	ТҮР	MAX	MIN	MAX	UNIT
t _{PLH}			0 15 -5		5.6	8	1	9.5	
t _{PHL}	A	Y	C _L = 15 pF		5.6	8	1	9.5	ns
t _{PZH}	05	V	0 15 -5		5.4	8	1	9.5	
t _{PZL}	ŌĒ	Y	C _L = 15 pF		5.4	8	1	9.5	ns
t _{PHZ}	ŌĒ	V	0 15 -5		7	9.7	1	11.5	ns
t _{PLZ}	ÛE	Y	C _L = 15 pF		7	9.7	1	11.5	
t _{PLH}	Α	Y			8.1	11.5	1	13	ns
t _{PHL}	А	ř	C _L = 50 pF		8.1	11.5	1	13	
t _{PZH}		Y			7.9	11.5	1	13	
t _{PZL}	ŌĒ	Ŷ	C _L = 50 pF		7.9	11.5	1	13	ns
t _{PHZ}	ŌĒ	Y	C _L = 50 pF		9.5	13.2	1	15	ns
t _{PLZ}		T	$O_L = 50 \text{ pr}$		9.5	13.2	1	15	115

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	Т	_A = 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	ТҮР	MAX	MIN	МАХ	UNIT
t _{PLH}	•	V	0 45 - 5		3.8	5.5	1	6.5	
t _{PHL}	А	Y	C _L = 15 pF		3.8	5.5	1	6.5	ns
t _{PZH}	<u> </u>	V	0 15 -5		3.6	5.1	1	6	
t _{PZL}	ŌĒ	Y	C _L = 15 pF		3.6	5.1	1	6	ns
t _{PHZ}		Y	0 45 - 5		4.6	6.8	1	8	
t _{PLZ}	ŌĒ	Ŷ	C _L = 15 pF		4.6	6.8	1	8	ns
t _{PLH}		X	0 50 - 5		5.3	7.5	1	8.5	
t _{PHL}	А	Y	C _L = 50 pF		5.3	7.5	1	8.5	ns
t _{PZH}	<u>AE</u>	X	0 50 - 5		5.1	7.1	1	8	
t _{PZL}	ŌĒ	Y	C _L = 50 pF		5.1	7.1	1	8	ns
t _{PHZ}	ŌĒ	Y	$C_{\rm r} = 50 \rm pF$		6.1	8.8	1	10	
t _{PLZ}	UE	r	C _L = 50 pF		6.1	8.8	1	10	ns

noise characteristics, $V_{CC} = 5 V$, $C_L = 50 pF$, $T_A = 25^{\circ}C$ (see Note 4)

	PARAMETER	MIN	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}	4.4		V
V _{IH(D)}	High-level dynamic input voltage	3.5		V
V _{IL(D)}	Low-level dynamic input voltage		1.5	V

NOTE 4: Characteristics are for surface-mount packages only.

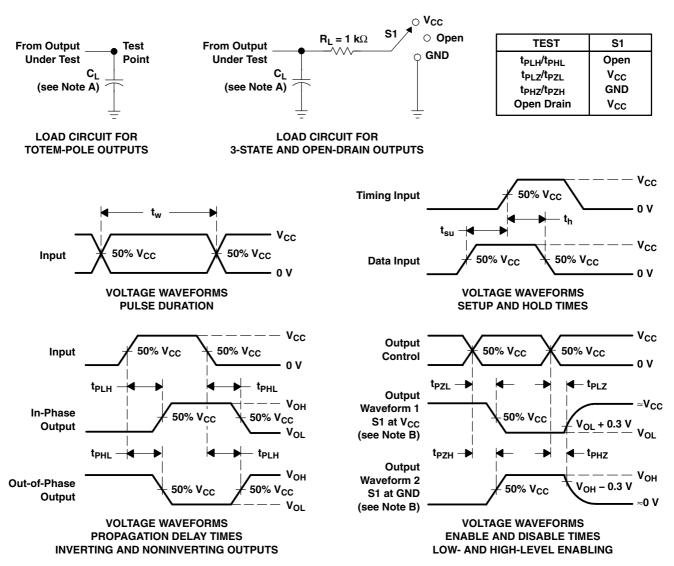
operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	NDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	14	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z₀ = 50 Ω , t_r \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHC125QPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA125Q	Samples
SN74AHC125QPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		HA125Q	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC125QPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHC125QPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Mar-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC125QPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74AHC125QPWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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